



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-10
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H7S3I8K6	23MR*485XXXB	A	9991	2024-09-10
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	104	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin - 3.5Ag	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	10x10	201	Bulk solder	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	23MR*485XXB		104.0000		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies	Other Organic Materials	2.618	mg	supplier	Silicon	Silicon	7440-21-3		2.513	mg	959714	24159				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.013	mg	4780	120				
				supplier	metallization	Copper (Cu)	7440-50-8		0.039	mg	14937	376				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.000	mg	85	2				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.006	mg	2475	62				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	427	11				
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	85	2				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.046	mg	17497	440				
				Substrate (A30228)	Copper & its alloys	40.183	mg	supplier	Substrate	Thermosetting resin (Including filler)	Proprietary		3.227	mg	80300	31026
								supplier	Substrate	Glass cloth	65997-17-3		18.484	mg	460000	177732
supplier	Substrate	Copper foil	7440-50-8						17.516	mg	435900	168421				
SVHC	Substrate	2-benzyl-2-dimethylamino-4-morpholinobutyrph	119313-12-1						0.016	mg	400	155				
supplier	Substrate	Naphtha (petroleum), heavy aromatic	64742-94-5						0.462	mg	11500	4443				
supplier	Substrate	TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6						0.462	mg	11500	4443				
SVHC	Substrate	1,3,5-Triazine-2,4,6-triamine	108-78-1						0.016	mg	400	155				
Die attach (ATB-125-12)	Precious metals	3.772	mg	supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-terminat	68610-41-3		2.452	mg	650000	23575				
				supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)oxiran	37382-79-9		0.943	mg	250000	9067				
				supplier	Glue or tape	Dapsone	80-08-0		0.226	mg	60000	2176				
				supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.075	mg	20000	725				
				supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorhydrin); e	25068-38-6		0.075	mg	20000	725				
Bonding wire (Cu)	Precious metals	0.771	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.744	mg	965500	7158				
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.024	mg	31000	230				
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.003	mg	3500	26				
Encapsulation (KE-G1250AAS)	Other inorganic materials	51.768	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0		46.591	mg	900000	447992				
				supplier	Molding Compound	Epoxy resin	Proprietary		2.744	mg	53000	26382				
				supplier	Molding Compound	Phenol resin	Proprietary		2.226	mg	43000	21404				
				supplier	Molding Compound	Carbon Black	1333-86-4		0.207	mg	4000	1991				
Solder Ball(96.5Sn3.5Ag)	Other Nonferrous metals & alloys	4.888	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		4.717	mg	965000	45355				
				supplier	Matte Sn	Impurities	Proprietary		0.171	mg	35000	1645				